







IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.

10/521333

Confirmation No. N/A

Applicant

Mitsuhiro Funaki et al.

Filed

January 18, 2005

TC/A.U. Examiner N/A N/A

Title

COPPER ALLOY, COPPER ALLOY PRODUCING

METHOD, COPPER COMPLEX MATERIAL, AND COPPER COMPLEX MATERIAL PRODUCING

METHOD

Docket No.
Customer No.

KOY-15896

040854

LETTER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir/Madam:

Applicant encloses herewith the required Declaration for the above-identified application. The \$130.00 fee to cover the late filing fee surcharge for the enclosed declaration was included in the filing fee sent on January 18, 2005.

If there are any further fees resulting from this communication not covered by the fee sent on January 18, 2005, please charge the same to Deposit Account No. 18-0160, Order No. KOY-15896.

Respectfully submitted,

RANKIN, HILL, PORTER & CLARK LLP

Bv

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or the date indicated below.

Signature of Person Mailing Paper

3/11/05

David E. Spaw

Date

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